



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



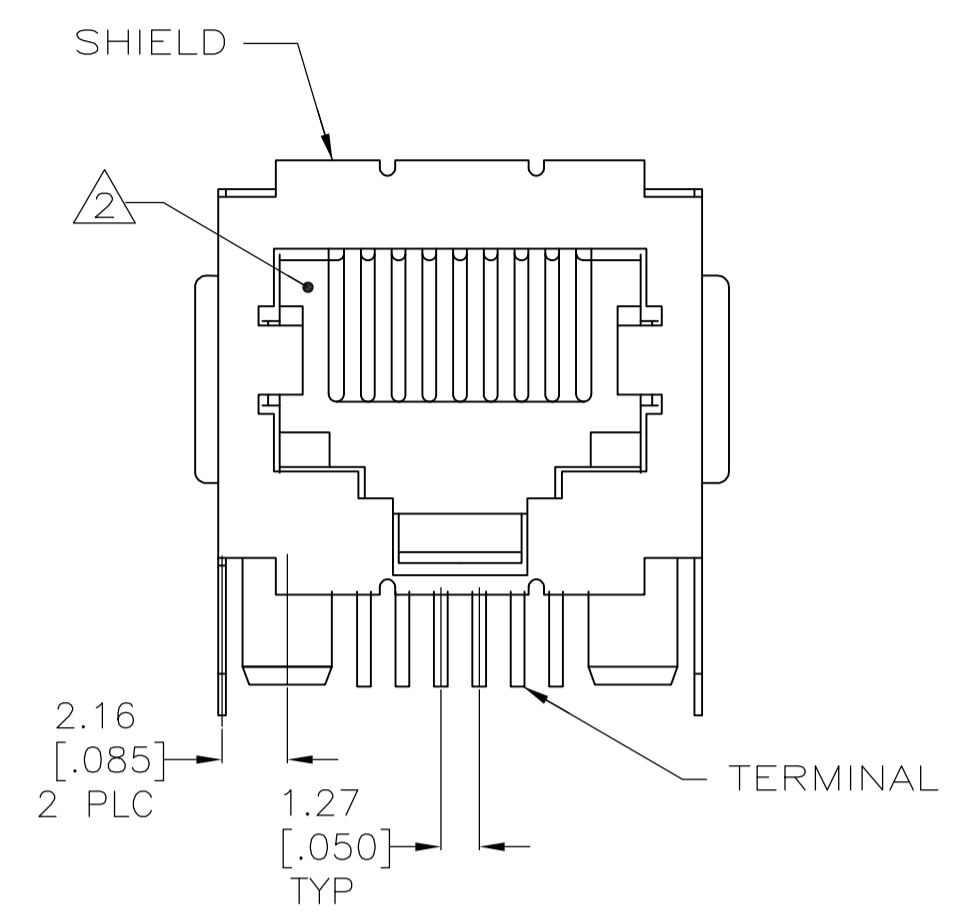
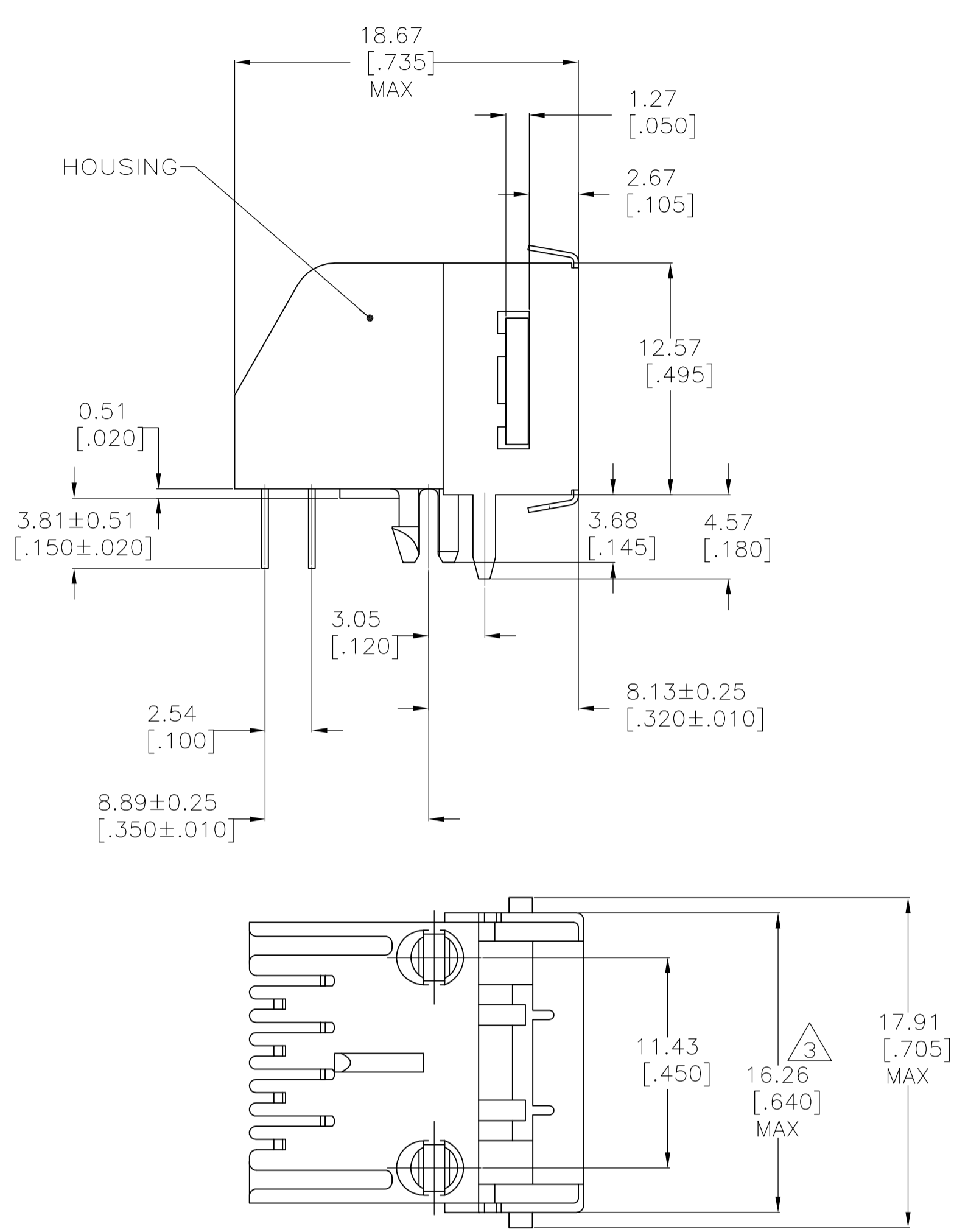
## Contact us

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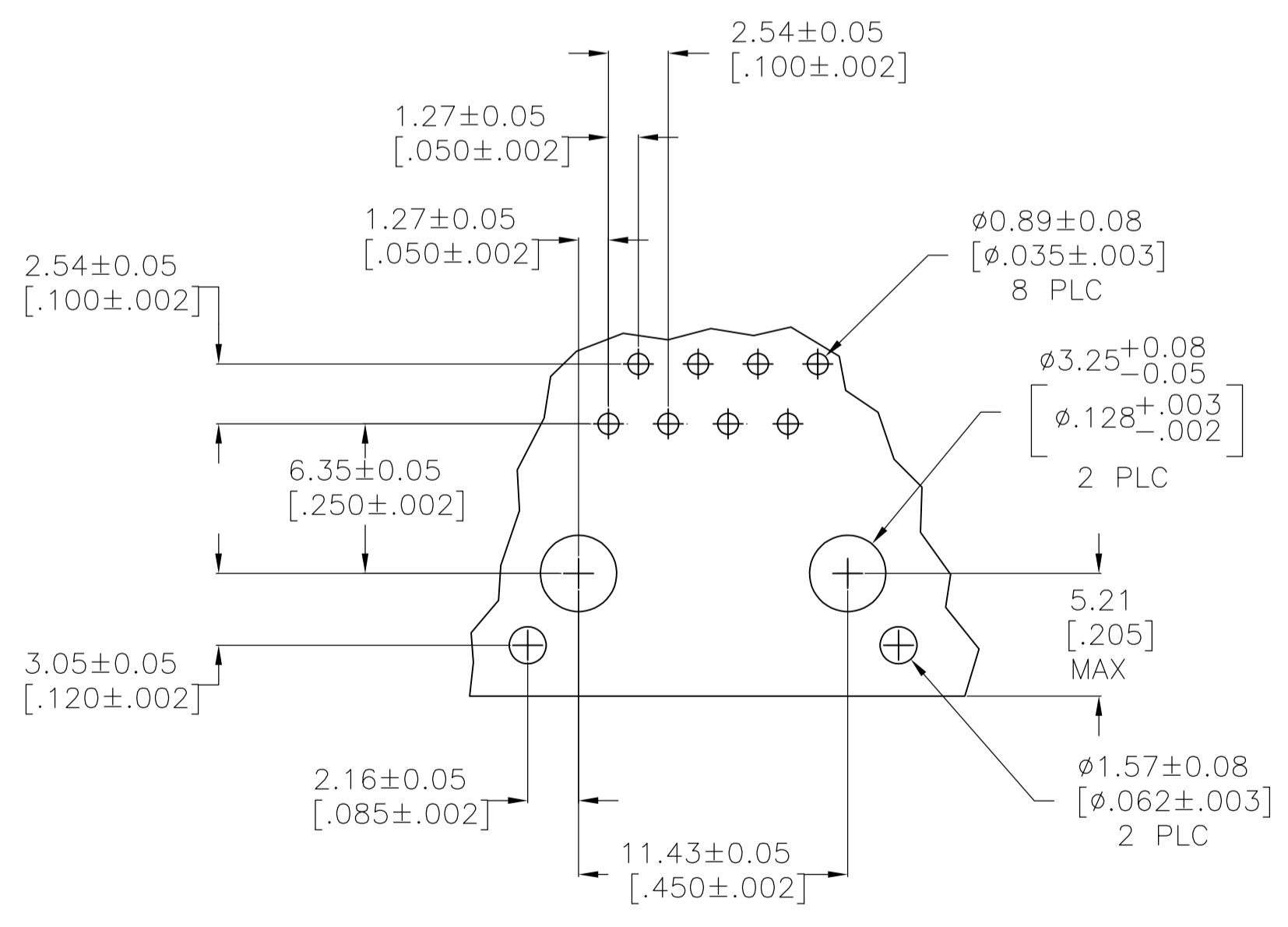
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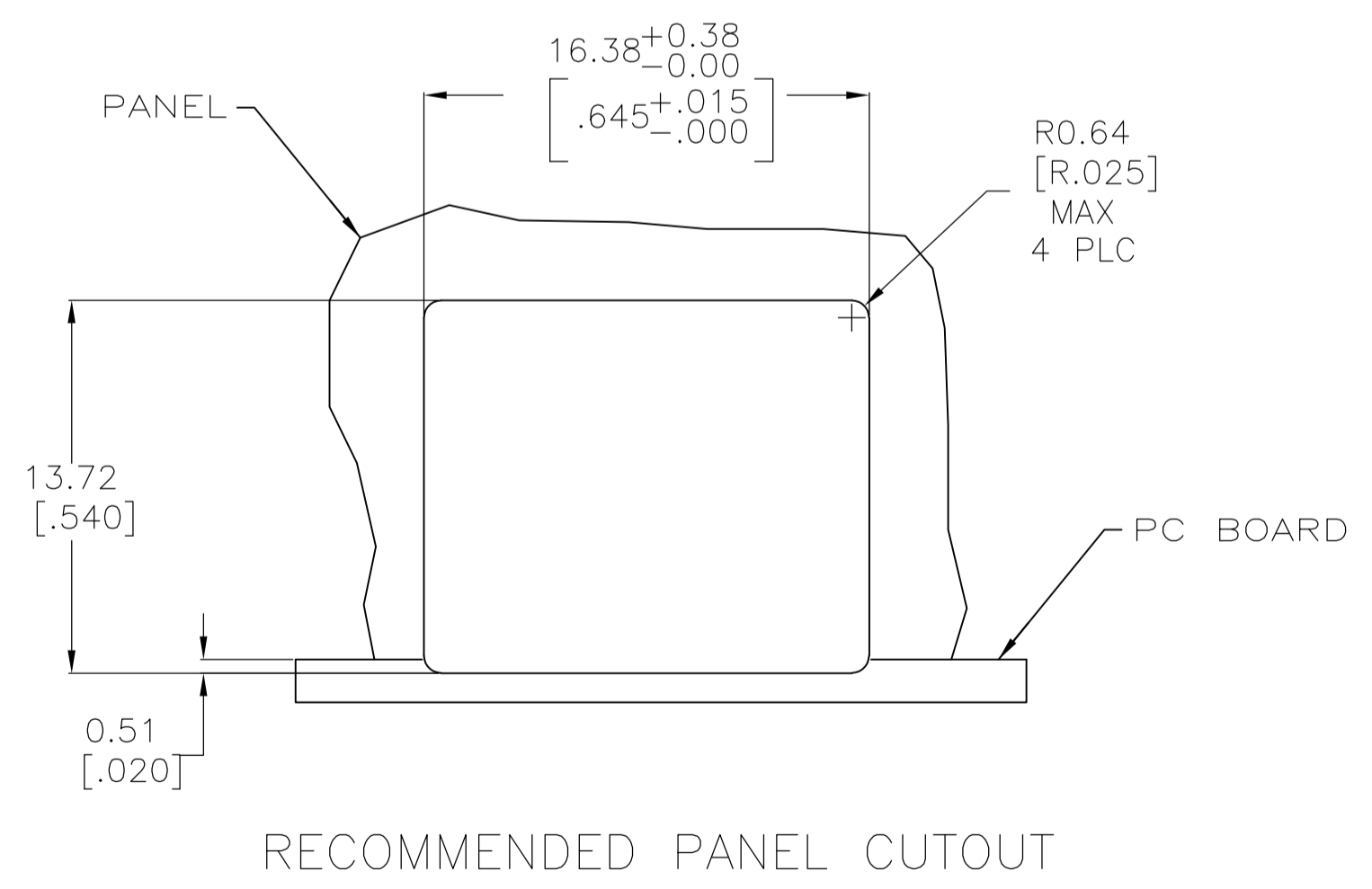




1. MATERIAL:  
 HOUSING (SEE TABLE) - COLOR: BLACK  
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27μm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm [.000150] THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] THICK NICKEL UNDERPLATE  
 SHIELD - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 3.0μm [.000120] MINIMUM THICK REFLOWED TIN
2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
3. DIMENSIONS MEASURED ALONG FRONT EDGES OF MATING FACE



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

YES	HIGH TEMP NYLON	5555141-3
NO	PBT POLYESTER	5555141-1
IR PROCESS COMPATIBLE	HOUSING MATERIAL	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN G. GARRETT/L.A. MAYER	04APR2005	 TE Connectivity
0 PLC ± -	1 PLC ± -	J. WESTMAN	04APR2005	
1 PLC ± -	2 PLC ± 0.13[.005]	S. FLICKINGER	04APR2005	NAME: MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS
2 PLC ± -	3 PLC ± -			PRODUCT SPEC: 108-1163
3 PLC ± -	4 PLC ± -			APPLICATION SPEC: 114-2048
4 PLC ± -	ANGLES ± -			SIZE: A1
MATERIAL: SEE NOTE 1	FINISH: SEE NOTE 1	WEIGHT: -	SCALE: 4:1	DRAWING NO: 00779
CUSTOMER DRAWING			SCALE: 4:1	SHEET: 1 OF 1